US00D327078S

United States Patent [19]

Nakao et al.

[11] **Patent Number: Des. 327,078**

[45] **Date of Patent: ** Jun. 16, 1992**

[54] **INSTRUMENT FOR TRANSFERRING BOATS FOR THERMAL TREATMENT OF SEMICONDUCTOR WAFERS**

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[73] Assignee: **Tel Sagami Limited**, Kanagawa, Japan

[**] Term: **14 Years**

[21] Appl. No.: **301,994**

[22] Filed: **Jan. 25, 1989**

[30] **Foreign Application Priority Data**

Jul. 25, 1988 [JP] Japan 63-29835

[52] **U.S. Cl.** **D15/144**

[58] **Field of Search** D15/144, 199; 219/390, 219/411; 414/222, 225, 226, 483; 432/6, 153, 239, 253, 258-261

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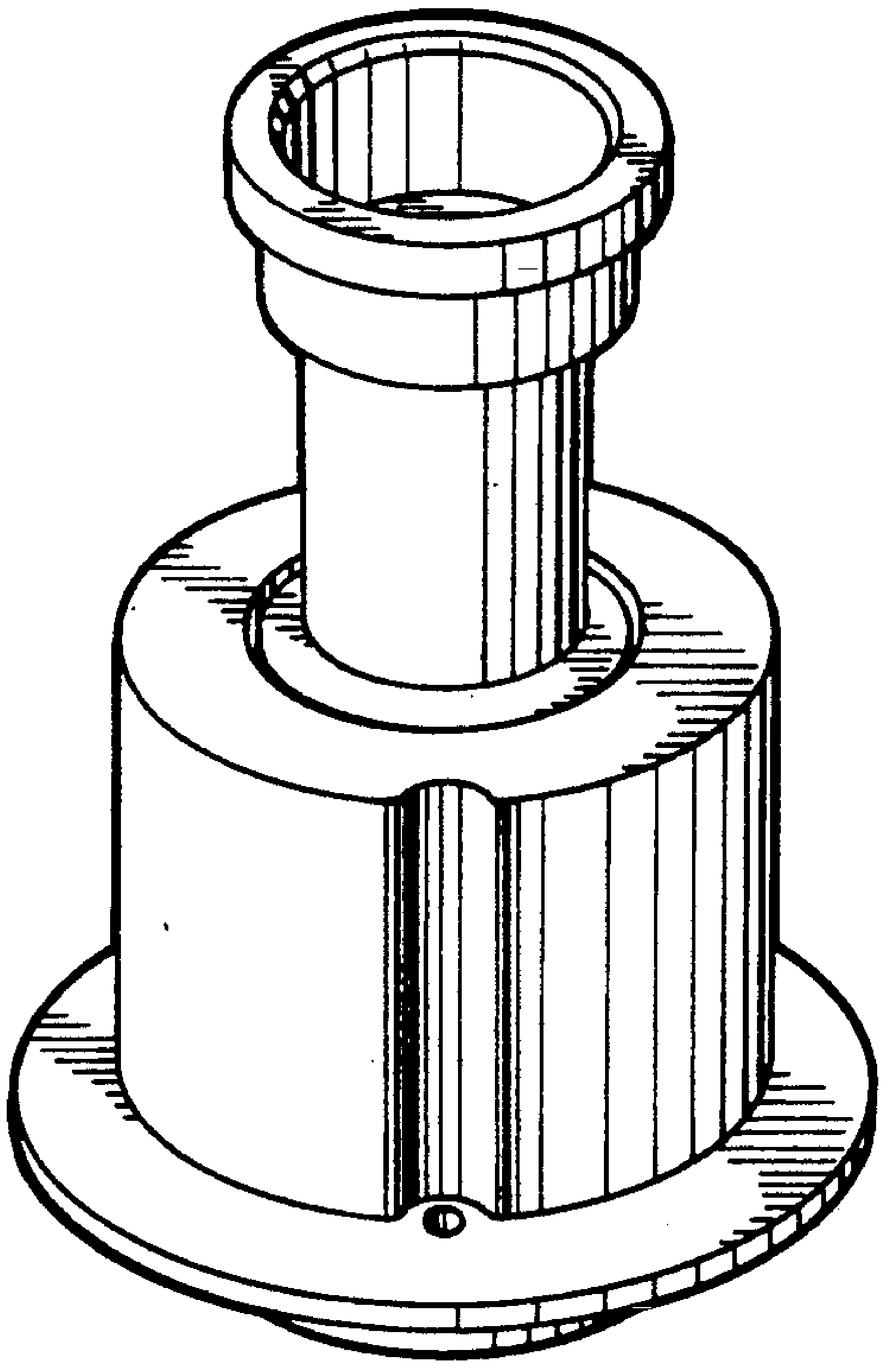
[57] **CLAIM**

The ornamental design for an instrument for transferring boats for thermal treatment of semiconductor wafers, as shown.

DESCRIPTION

FIG. **1** is a front elevational view of an instrument for transferring boats for thermal treatment of semiconductor wafers showing our new design;
FIG. **2** is an elevational view, the remainder of the cylindrical member being the same throughout in appearance;
FIG. **3** is a top plan view;
FIG. **4** is a bottom plan view;
FIG. **5** is an elevational view thereof;
FIG. **6** is a top perspective view; and,
FIG. **7** is a bottom perspective view thereof.



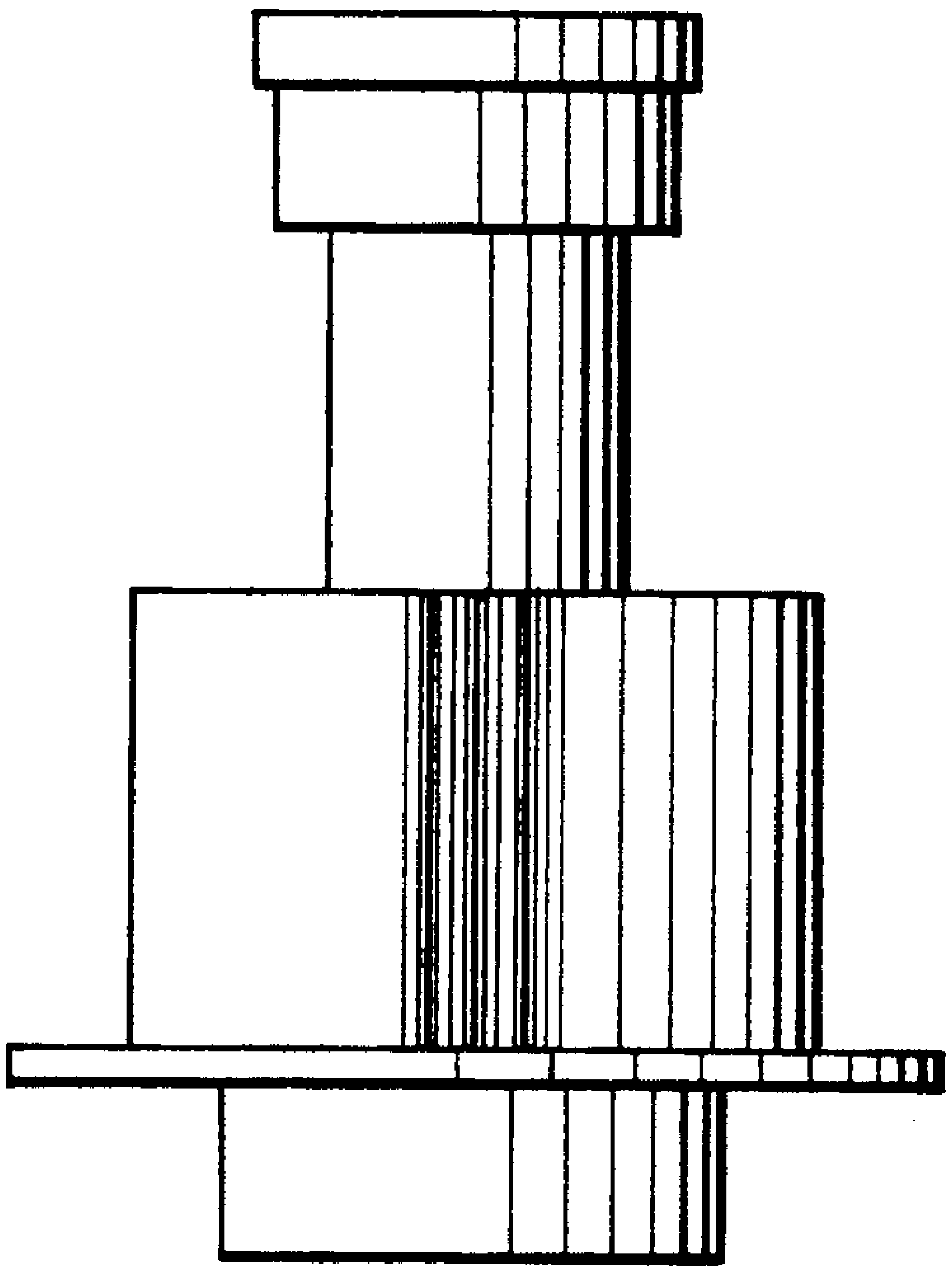


FIG.1

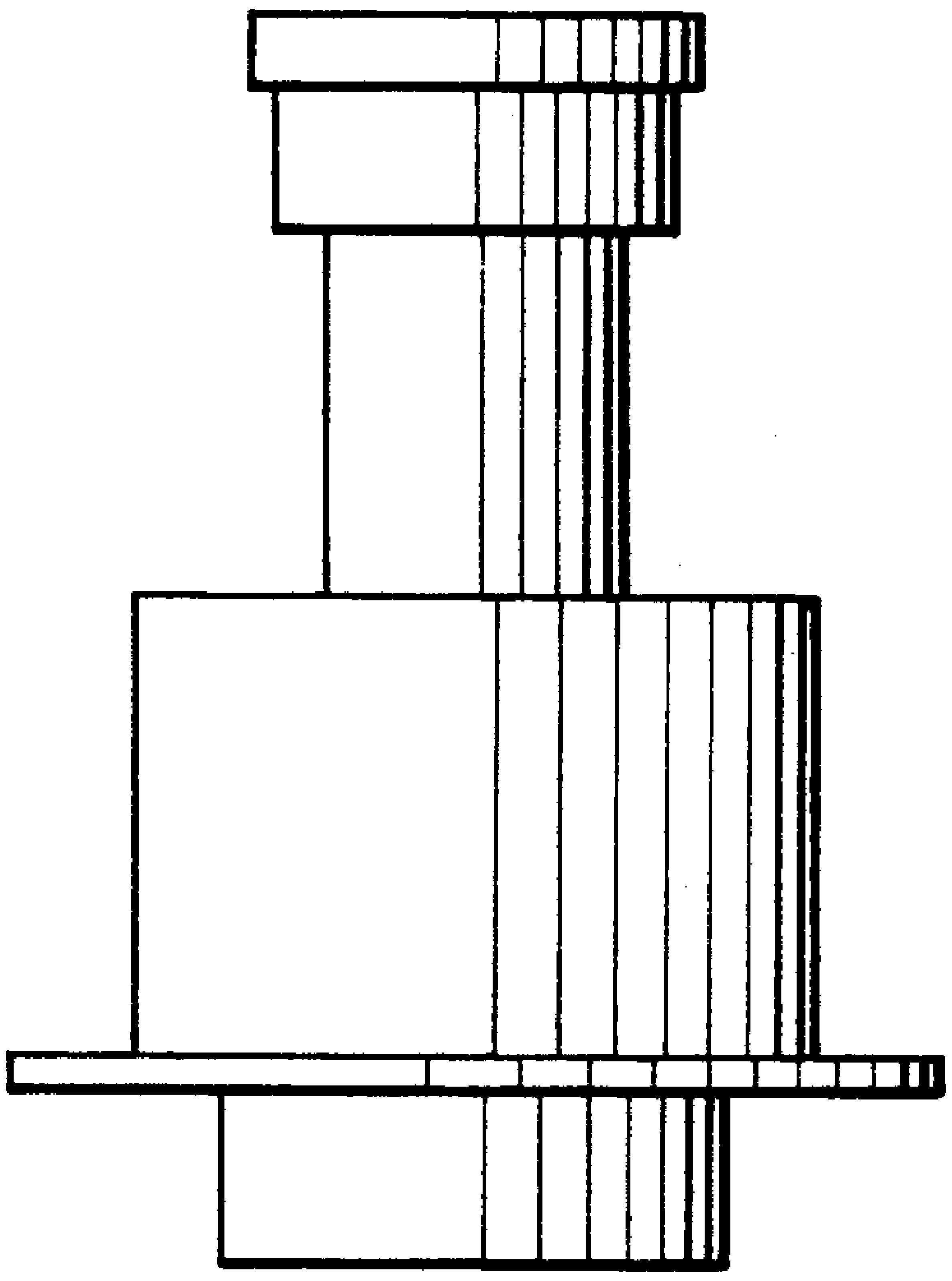


FIG.2

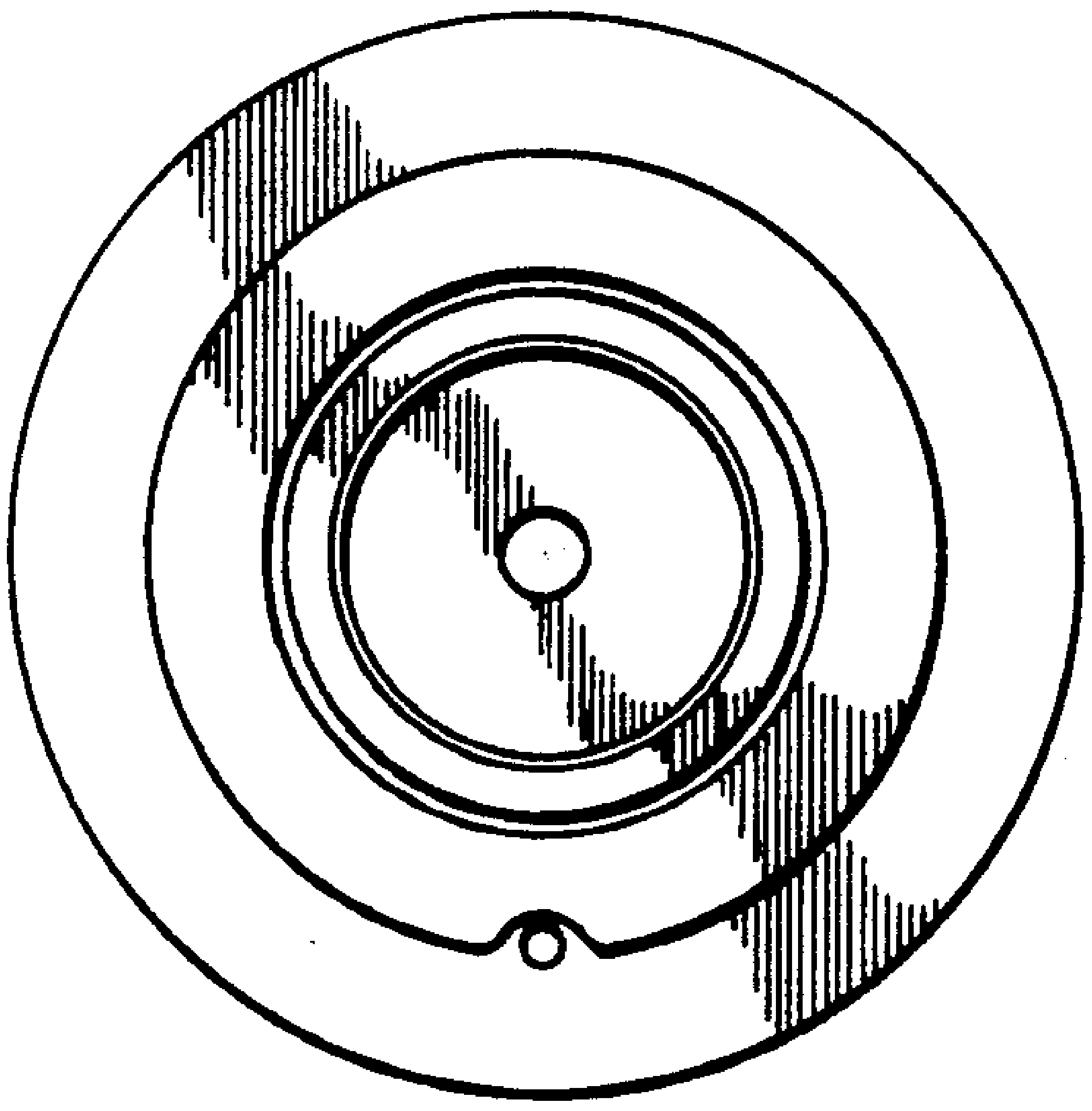


FIG.3

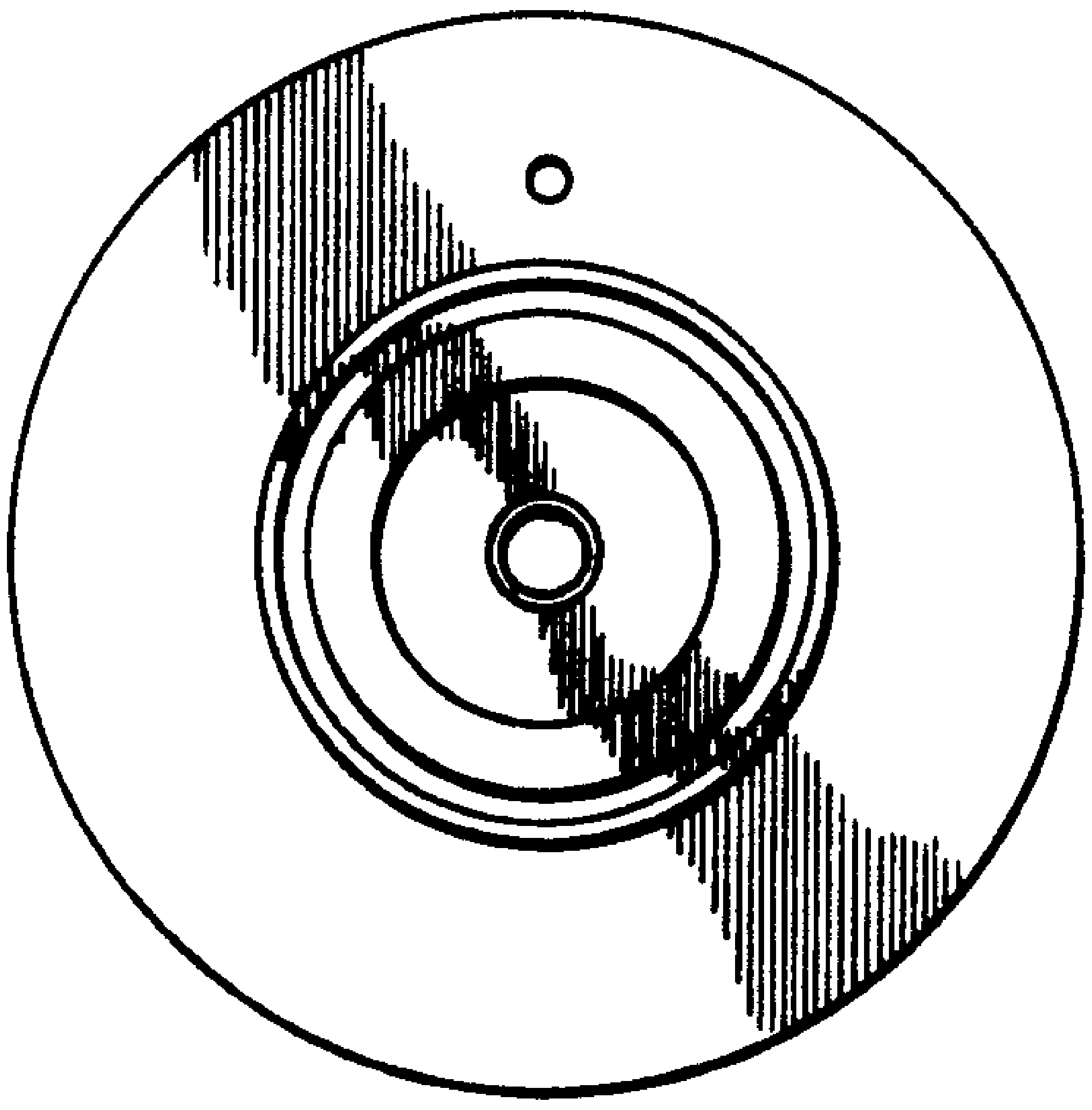


FIG.4

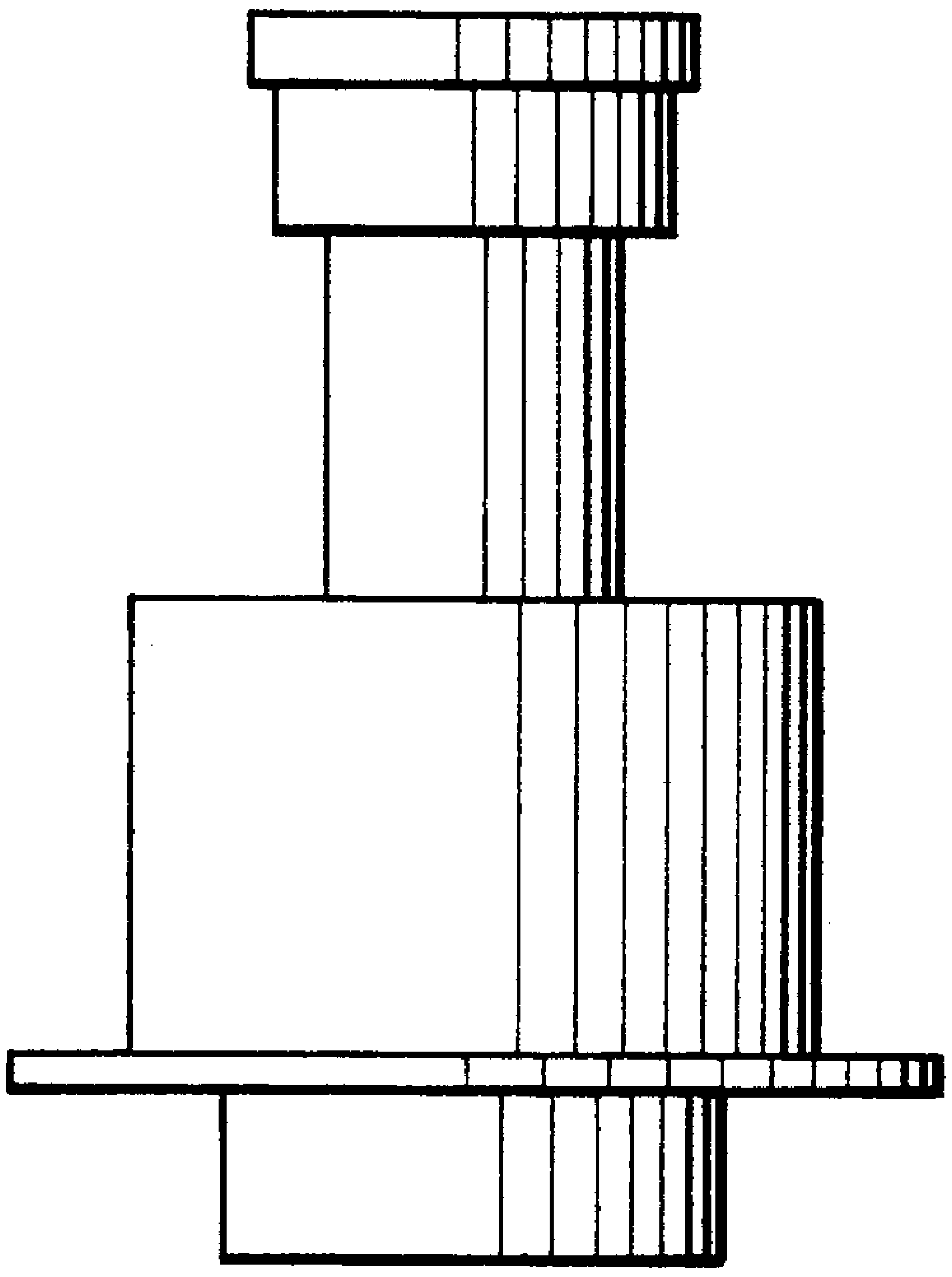


FIG.5

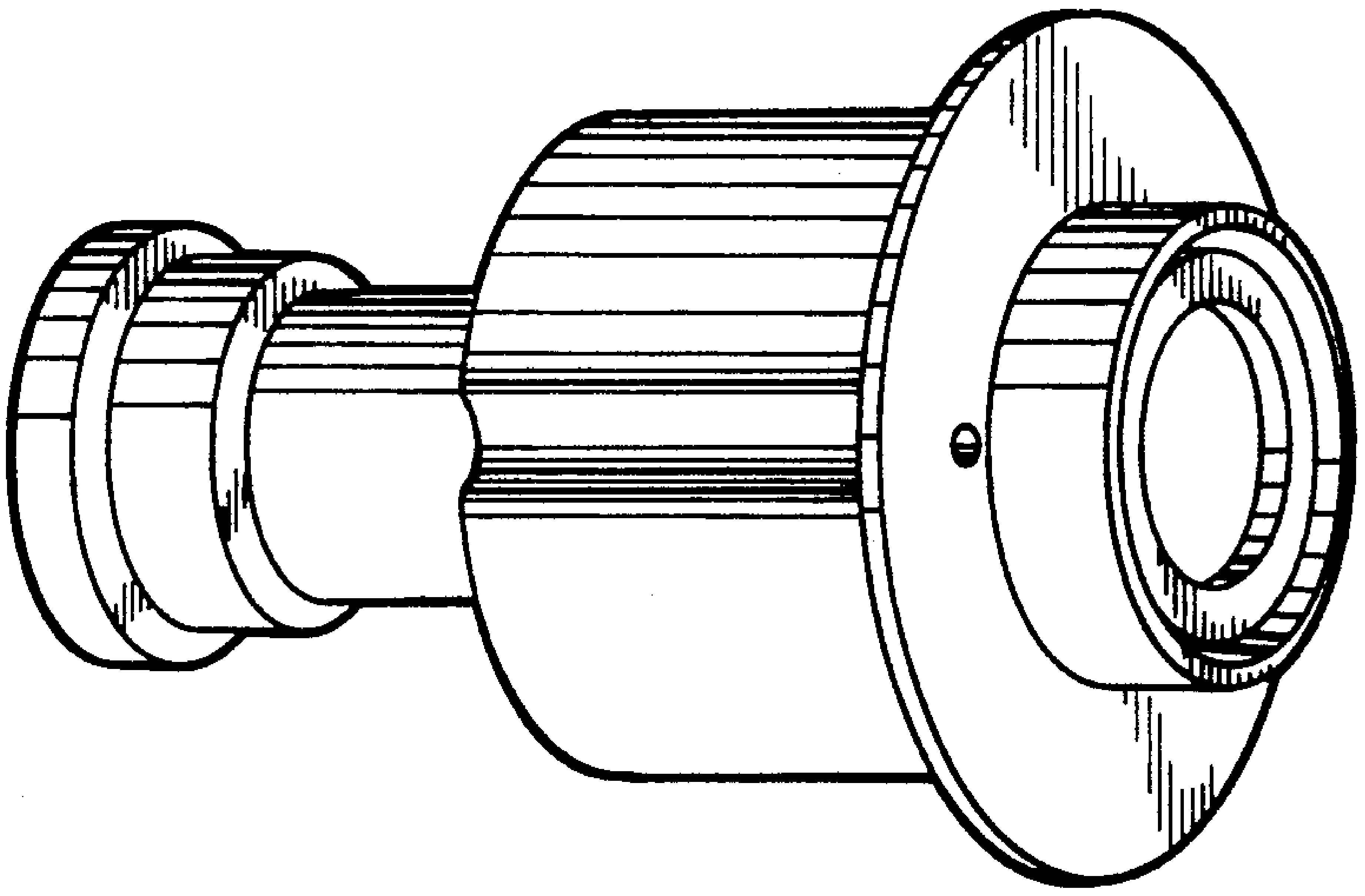


FIG.7

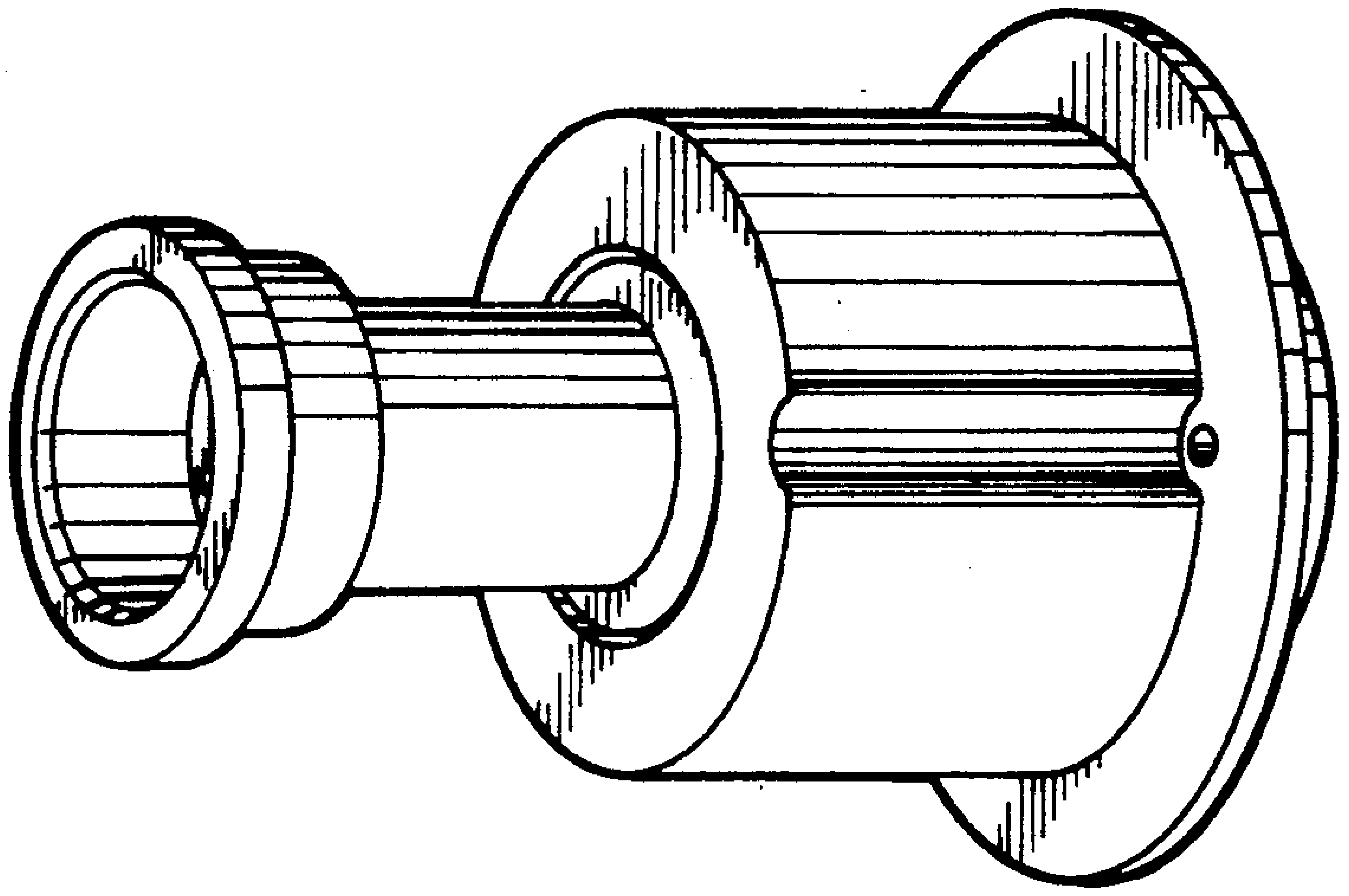


FIG.6